

Application No.: 018865-004210US
Applicant: Joshi et al.
Title: FLIP CHIP IN LEADED MOLDED PACKAGE etc.
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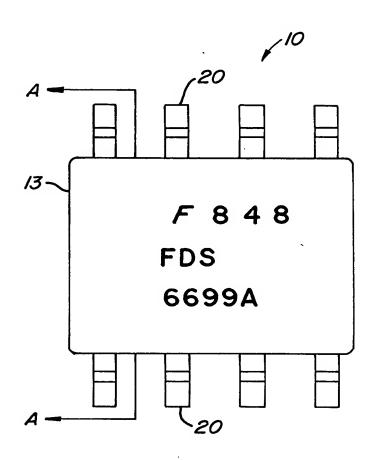


FIG. IA.

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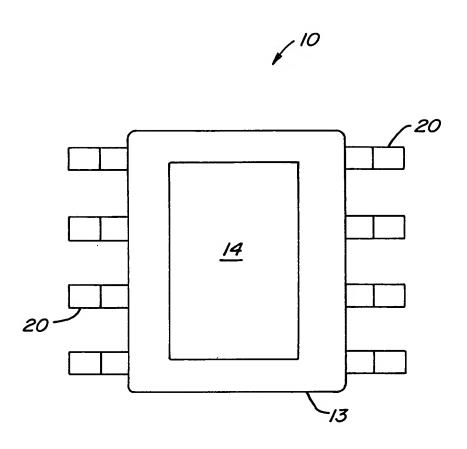


FIG. IB.



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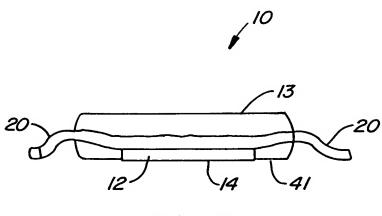


FIG. IC.

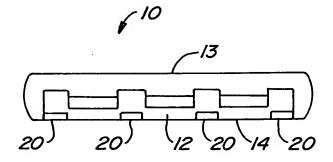


FIG. ID.



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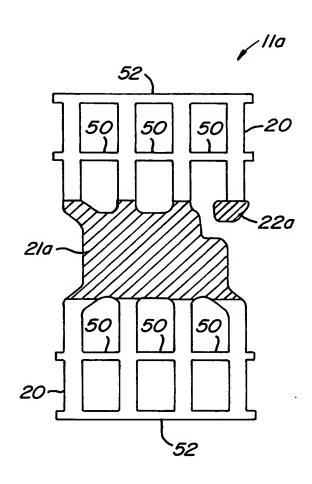


FIG. 2.



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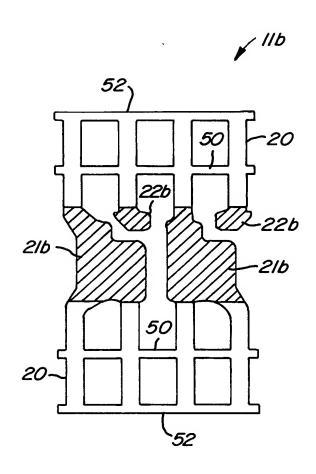


FIG. 3.



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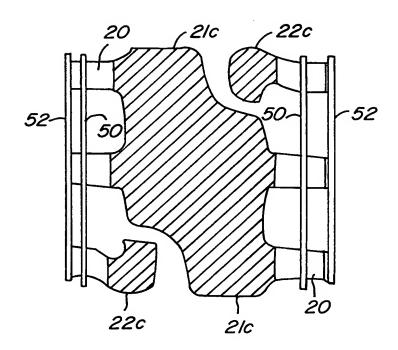


FIG. 3A.



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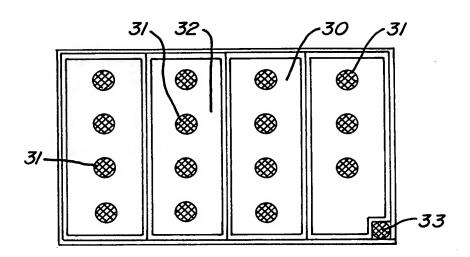


FIG. 4.



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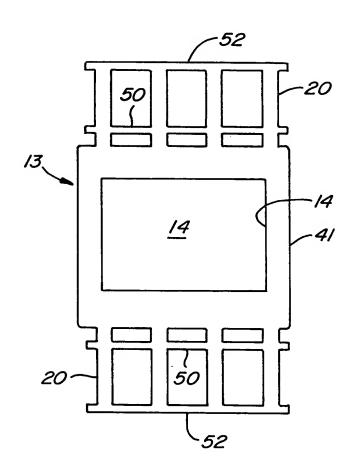


FIG. 5.



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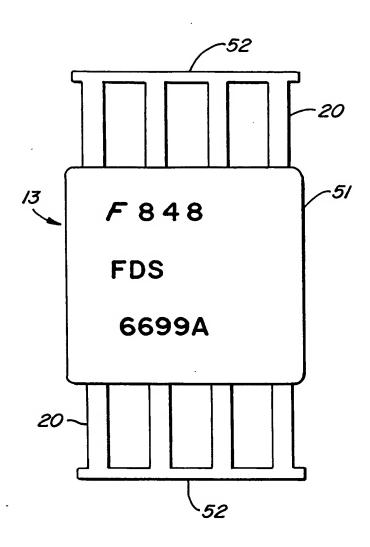


FIG. 6.

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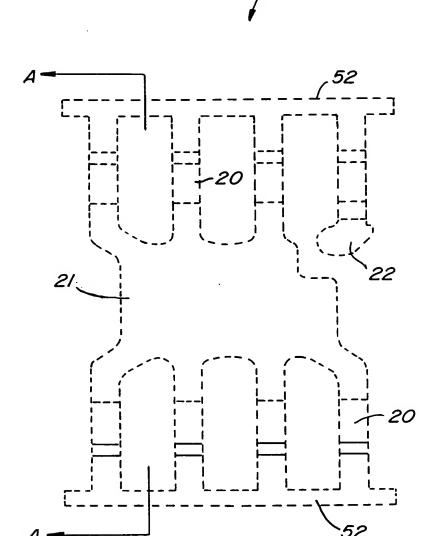


FIG. 7A.

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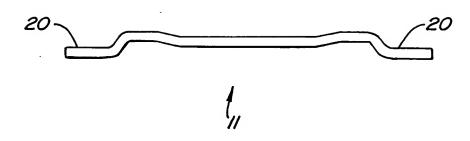


FIG. 7B.